

ABSTRACT OF THE DISCLOSURE

93 A method for molding and soldering electrical connection pads to the electrical connection-receiving zones of electronic components or circuits includes an operation for the injection of conductive liquid alloy into a guide open at one end placed so as to face the connection-receiving zone of the component. The guide is formed by two separable parts, a mold and an injection matrix, the mold and the injection matrix including passages, with a narrowing of the guide at the level of the separation of the parts, and the parts of the guide are separated while the alloy is in the liquid state. Such a method may find particular application to, as an example, making connection pads for substrates or electronic components.

REMARKS

Favorable consideration of this application, as presently amended, is respectfully requested.

The present preliminary amendment is submitted to correct for minor informalities in the above-identified application.

By the present preliminary amendment, the multiple dependency of Claim 22 has been cancelled. Further, the subject matter of the cancelled multiple dependency is now set forth in new dependent Claims 23-28. The Abstract has also been amended by the present response to be in more proper format under United States practice.